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**NEW!**

## BluTac 60



### Advantages:

- ?? Low Thermal Impedance: 0.05 C/W/in<sup>2</sup>
- ?? Low Closure Force: 15psi
- ?? Free Standing Film, contains no substrate
- ?? Proprietary mass-adhesive system with unique features
- ?? Easy to handle
- ?? Reversible Thermoplastic adhesive bond

### Description:

BluTac 60 is the ultimate thermal interface material. It seems dry to the touch when handled; yet it sticks to the heat sink surface at room temperature. This new ORCUS material is a Free Standing Film. It is self-supporting; there is no substrate to increase thermal impedance. It is eminently manufacturing friendly. When reflowed during initial equipment power-up it forms a low thermal impedance thermoplastic adhesive bond between component and heat sink. The 60°C phase change temperature is suitable for many microprocessors and other power device applications. BluTac 60 is perfect to use as die-cut parts on rolls in conjunction with the ORCUS Peel and Place Parts Dispenser.

### BluTac 60 Typical Characteristics:

Standard Thickness: 5 mils  
Phase Change Temperature: 60°C  
Density: 2.0 g/cc  
Thermal Impedance: 0.05 C/W/in<sup>2</sup> at 15psi  
Maximum Use Temperature: 200°C  
Dielectric Strength: 375 V/mil (ASTM 149)